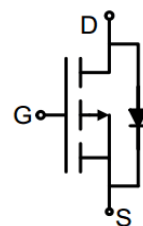
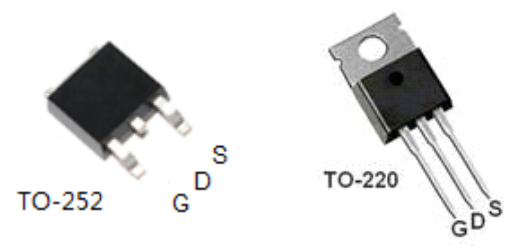


# P-Channel Trench MOSFET

<p><b>Description</b></p> <p>The G65P06 uses advanced trench technology to provide excellent <math>R_{DS(ON)}</math>, low gate charge. It can be used in a wide variety of applications.</p> <p><b>General Features</b></p> <ul style="list-style-type: none"> <li>● <math>V_{DS}</math> -60V</li> <li>● <math>I_D</math> (at <math>V_{GS} = -10V</math>) -65A</li> <li>● <math>R_{DS(ON)}</math> (at <math>V_{GS} = -10V</math>) &lt; 18m<math>\Omega</math></li> <li>● 100% Avalanche Tested</li> <li>● RoHS Compliant</li> </ul> <p><b>Application</b></p> <ul style="list-style-type: none"> <li>● Power switch</li> <li>● DC/DC converters</li> </ul>		 <p>Schematic diagram</p> 	
<b>Device</b>	<b>Package</b>	<b>Marking</b>	<b>Packaging</b>
G65P06K	TO-252	G65P06	2500pcs/Reel
G65P06T	TO-220	G65P06	50pcs/Tube

## Absolute Maximum Ratings $T_C = 25^\circ C$ , unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-60	V
Continuous Drain Current	$I_D$	-65	A
Pulsed Drain Current (note1)	$I_{DM}$	-260	A
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Power Dissipation	$P_D$	130	W
Operating Junction and Storage Temperature Range	$T_J, T_{stg}$	-55 To 175	$^\circ C$

## Thermal Resistance

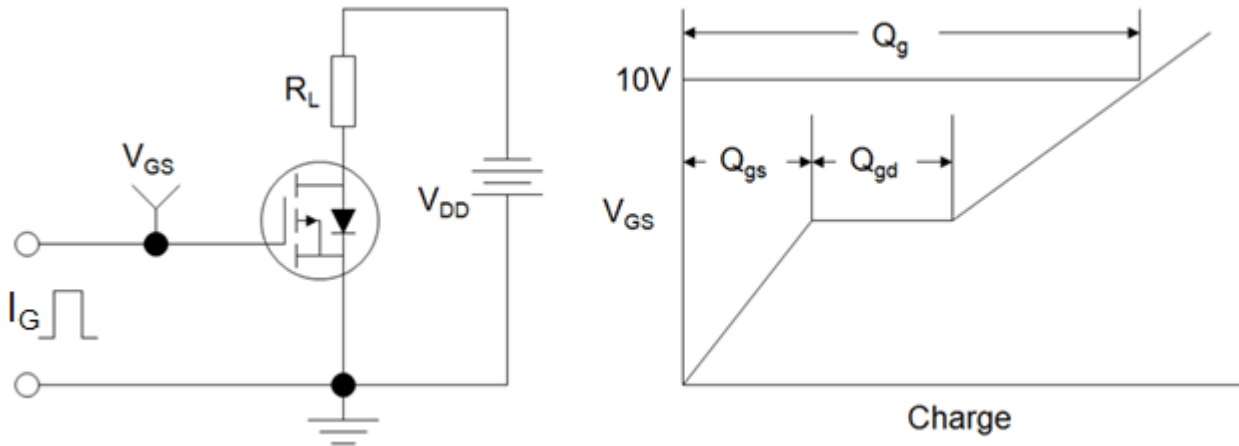
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (note2)	$R_{thJc}$	1.15	$^\circ C/W$

Specifications $T_J = 25^\circ\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Parameters</b>						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-60	--	--	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -60V, V_{GS} = 0V$	--	--	-1	$\mu A$
Gate-Source Leakage	$I_{GSS}$	$V_{GS} = \pm 20V$	--	--	$\pm 100$	nA
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-2	-2.6	-3.5	V
Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -20A$	--	13	18	m $\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = -5V, I_D = -20A$	--	25	--	S
<b>Dynamic Parameters (note4)</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V,$ $V_{DS} = -25V,$ $f = 1.0\text{MHz}$	--	5814	--	pF
Output Capacitance	$C_{oss}$		--	483	--	
Reverse Transfer Capacitance	$C_{rss}$		--	234	--	
Total Gate Charge	$Q_g$	$V_{DS} = -30V,$ $I_D = -20A,$ $V_{GS} = -10V$	--	75	--	nC
Gate-Source Charge	$Q_{gs}$		--	16	--	
Gate-Drain Charge	$Q_{gd}$		--	19	--	
Turn-on Delay Time	$t_{d(on)}$	$V_{DS} = -30V,$ $R_L = 1.5\Omega,$ $V_{GS} = -10V,$ $R_G = 3\Omega$	--	18	--	nS
Turn-on Rise Time	$t_r$		--	20	--	
Turn-off Delay Time	$t_{d(off)}$		--	55	--	
Turn-off Fall Time	$t_f$		--	35	--	
<b>Drain-Source Body Diode Characteristics</b>						
Body Diode Voltage (note3)	$V_{SD}$	$I_S = -20A, V_{GS} = 0V$	--	--	-1.2	V
Single pulse avalanche energy (note5)	$E_{AS}$		--	722	--	mJ
Reverse Recovery Time	$t_{rr}$	$I_S = -20A, V_{GS} = 0V$	--	0.13	--	$\mu S$
Reverse Recovery Charge	$Q_{rr}$	$di/dt = -100A/\mu s$	--	0.77	--	$\mu C$

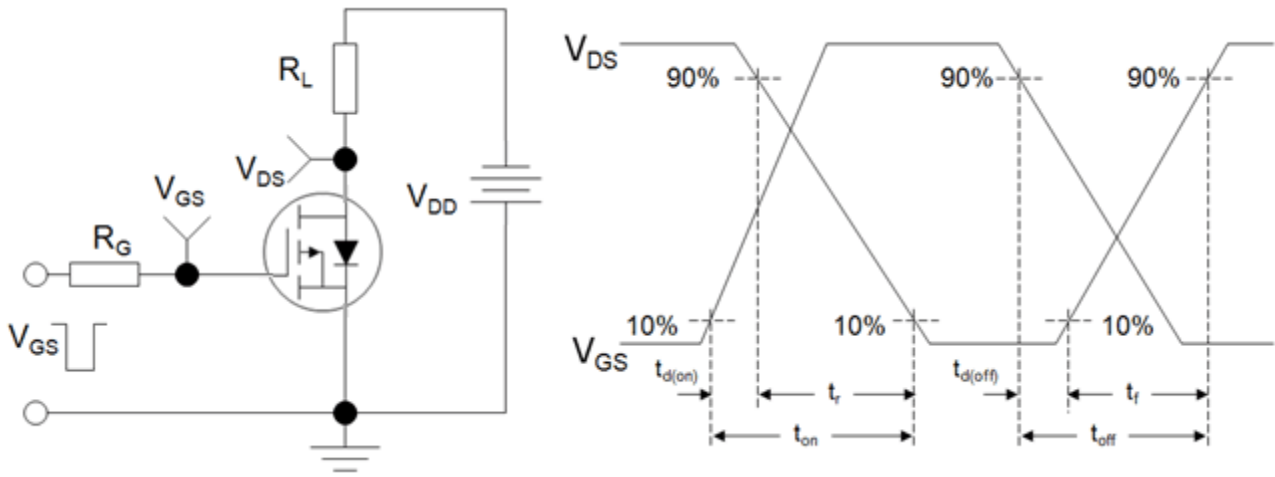
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production
5.  $E_{AS}$  condition:  $T_J = 25^\circ\text{C}, V_{DD} = -30V, V_G = -10V, L = 0.5\text{mH}, R_G = 25\Omega$

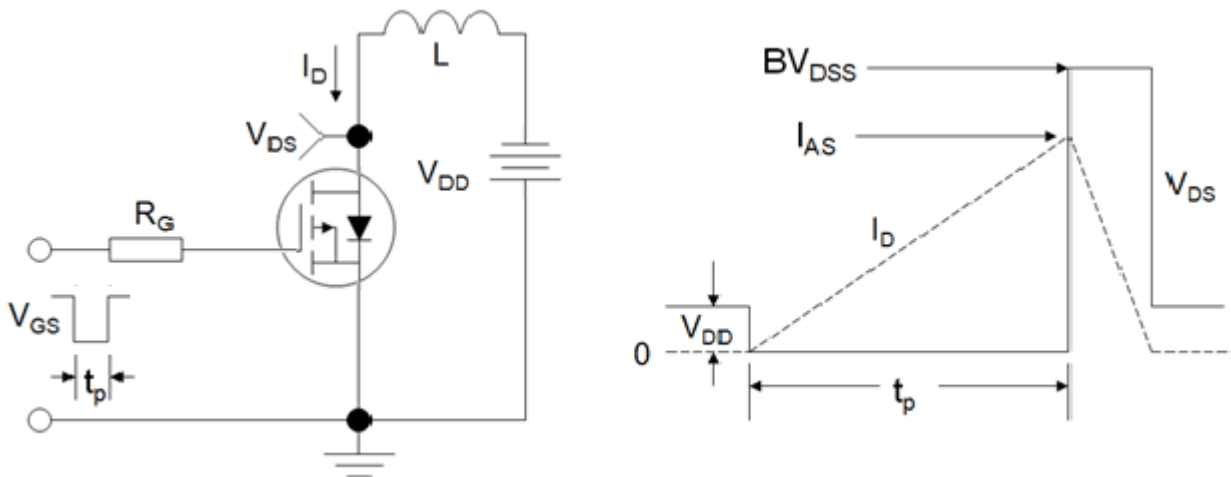
Gate Charge Test Circuit



Switch Time Test Circuit



EAS Test Circuit



Typical Electrical and Thermal Characteristics (Curves)

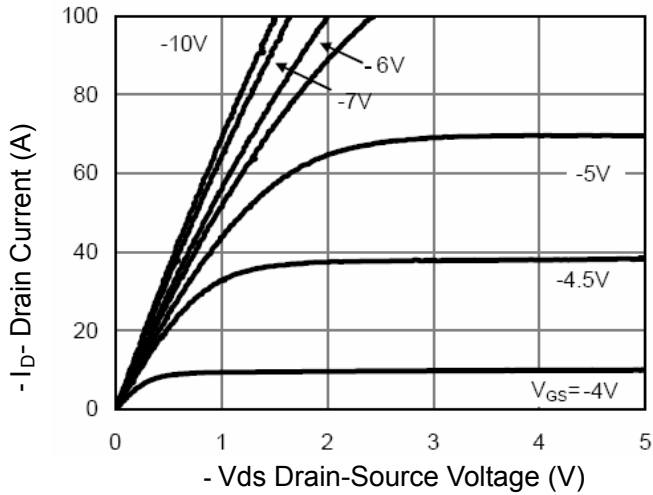


Figure 1 Output Characteristics

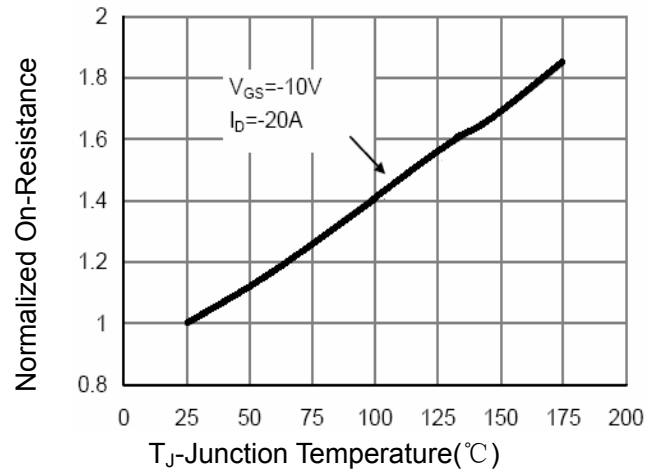


Figure 4 Rdson-Junction Temperature

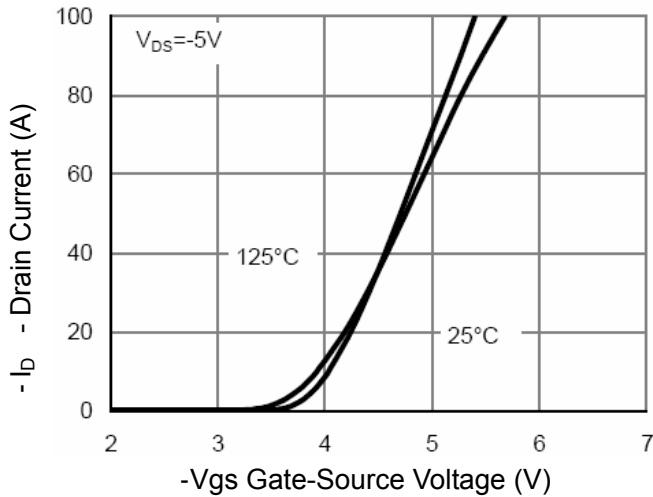


Figure 2 Transfer Characteristics

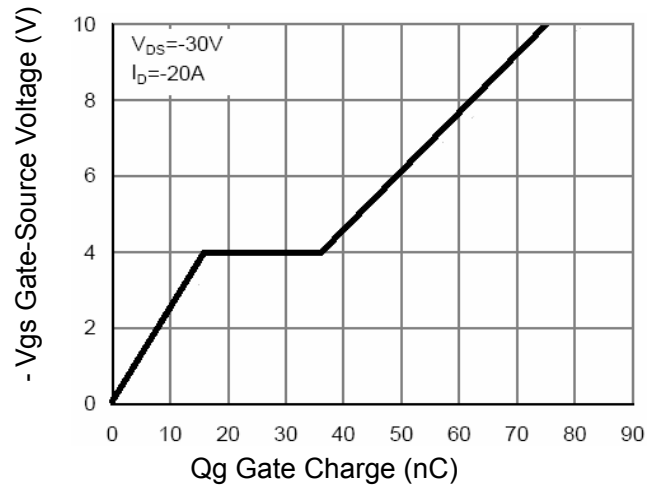


Figure 5 Gate Charge

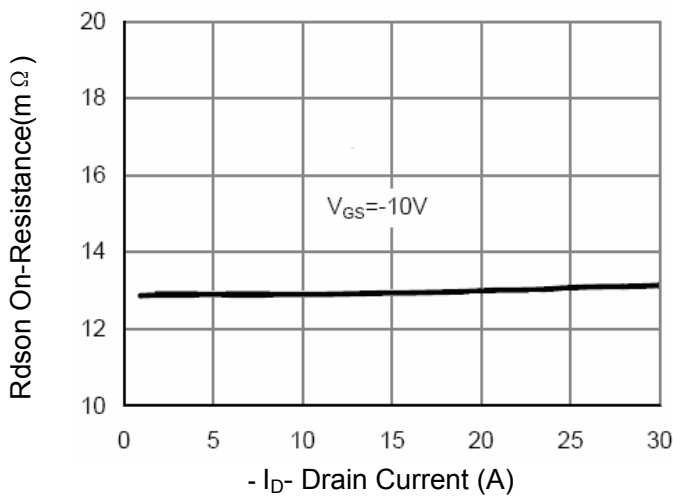


Figure 3 Rdson- Drain Current

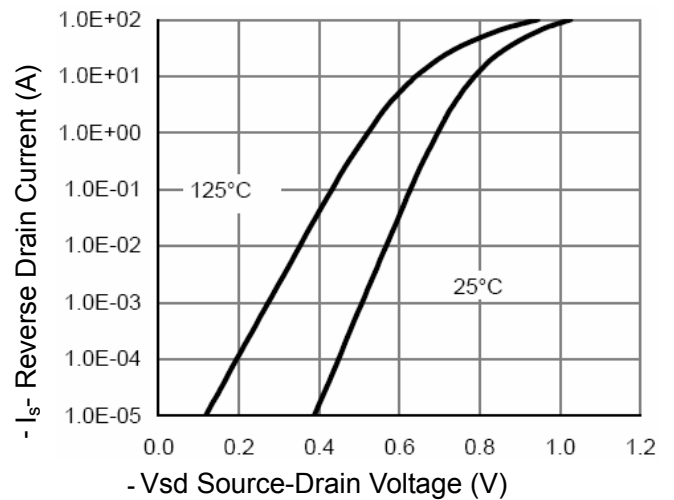


Figure 6 Source- Drain Diode Forward

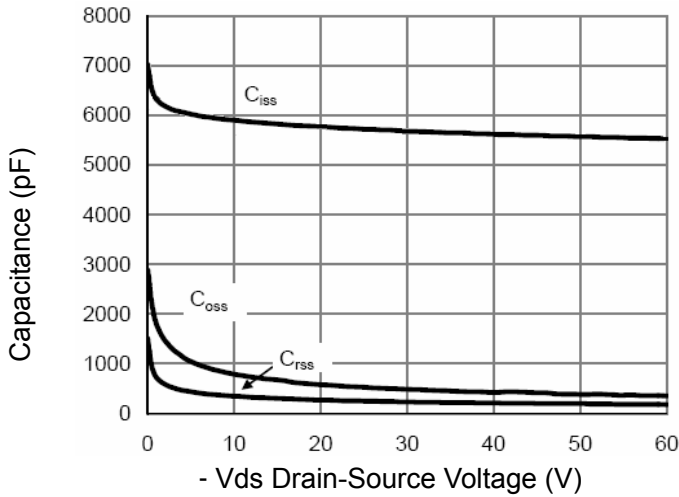


Figure 7 Capacitance vs Vds

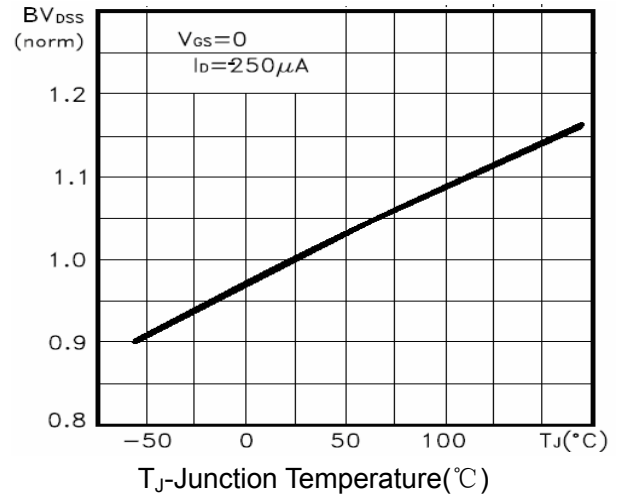


Figure 9  $BV_{DSS}$  vs Junction Temperature

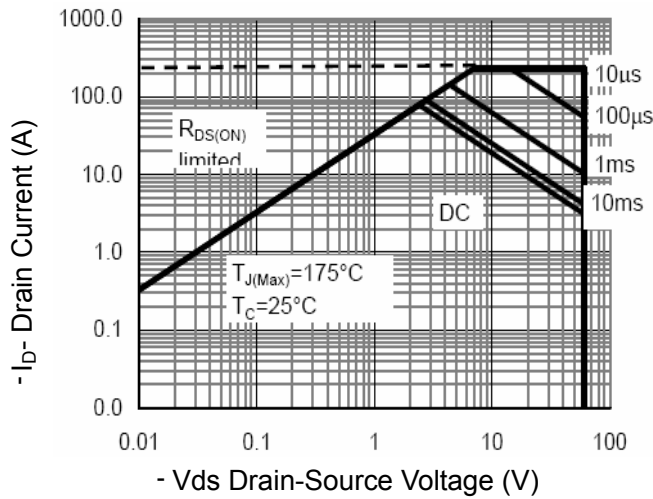


Figure 8 Safe Operation Area

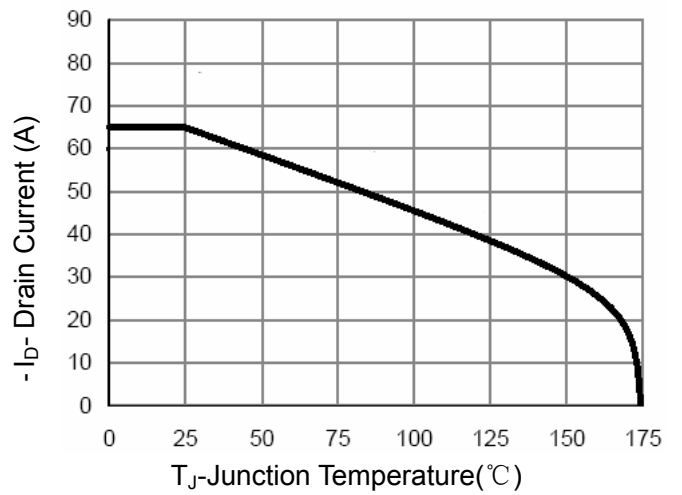


Figure 10  $I_D$  Current Derating vs Junction Temperature

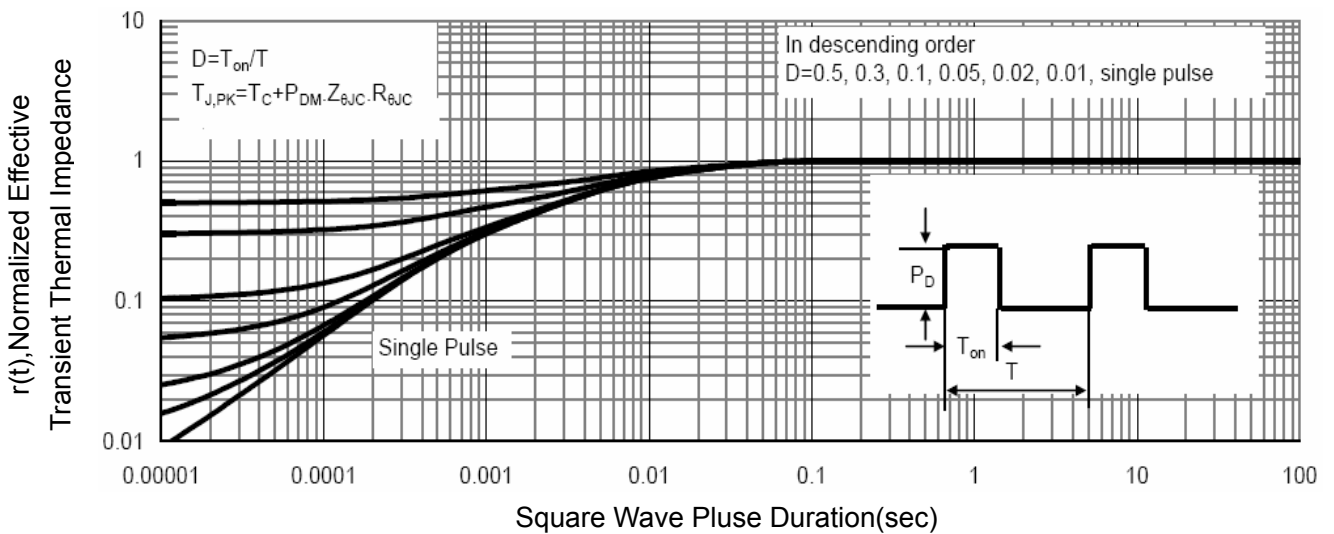
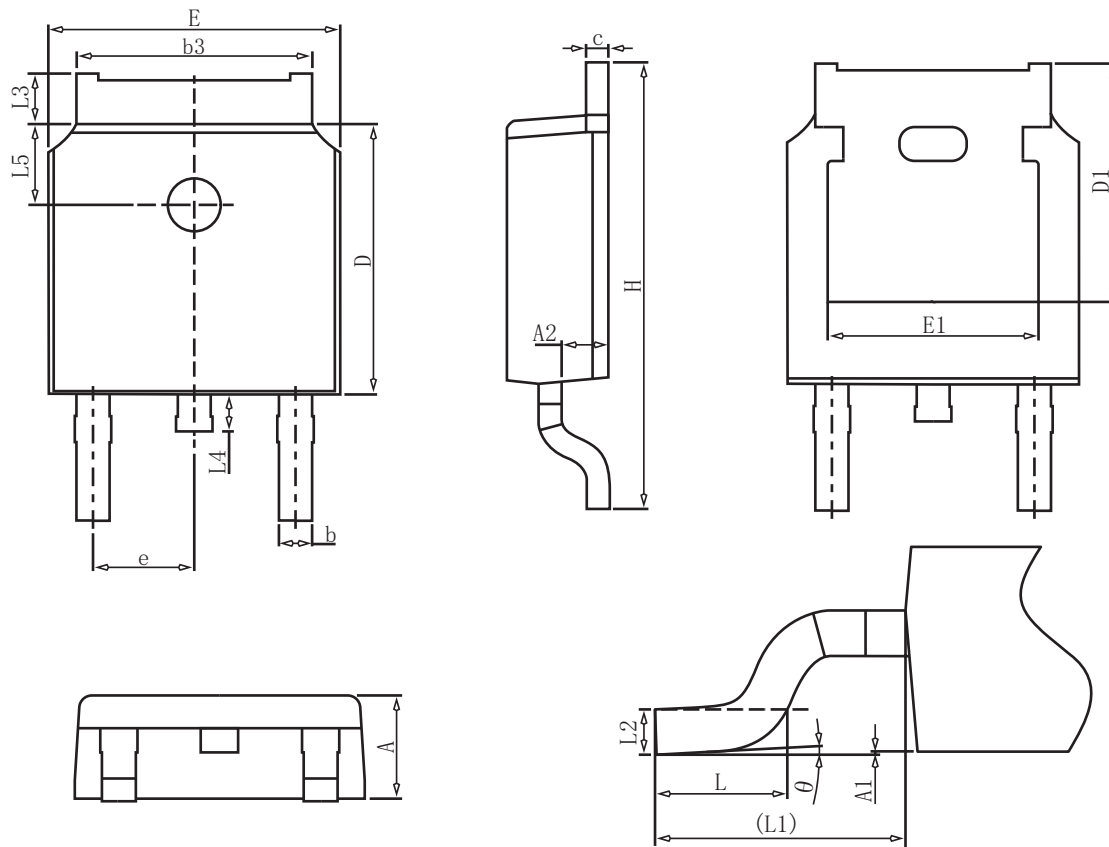


Figure 11 Normalized Maximum Transient Thermal Impedance

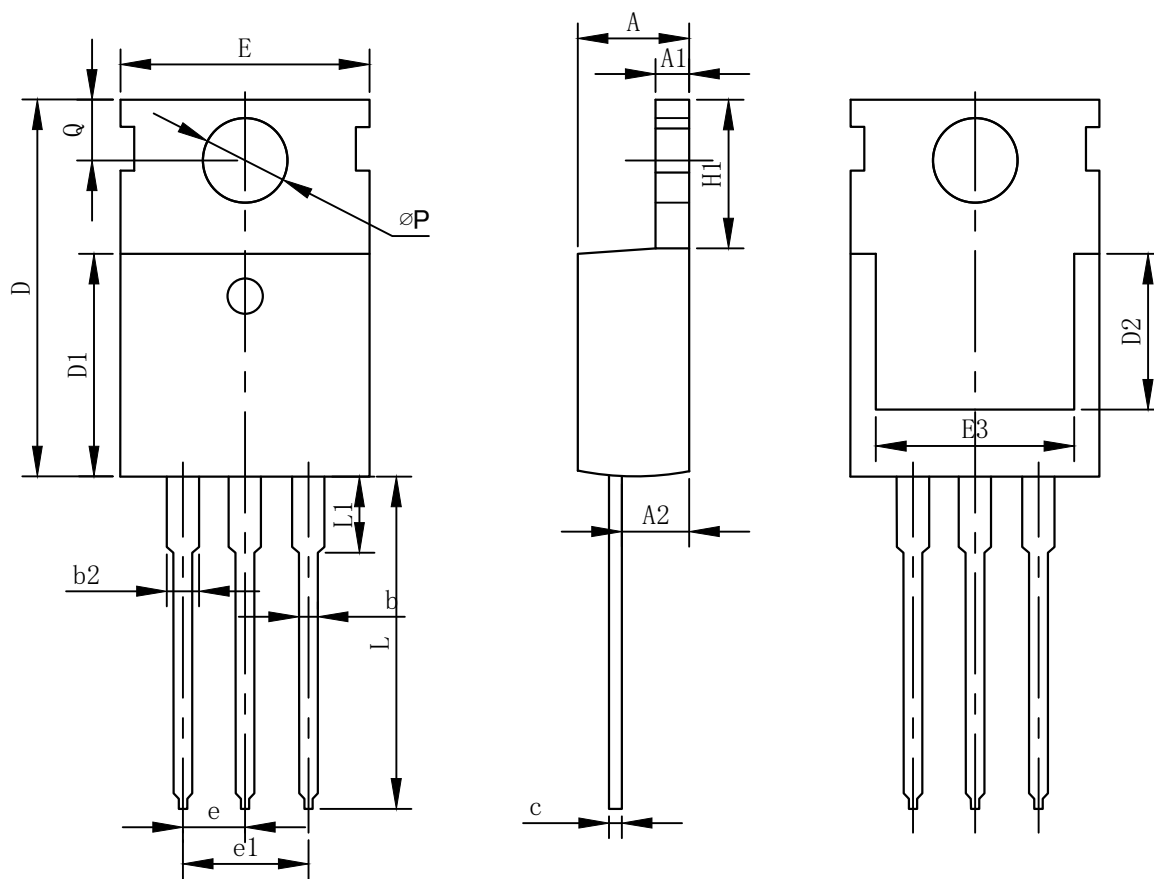
TO-252 Package information



COMMON DIMENSIONS

SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	-	0.20
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.50
c	0.43	0.53	0.63
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.80
E1	4.63	-	-
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
L5	1.65	1.80	1.95
theta	0°	-	8°

### TO-220 Package information



COMMON DIMENSIONS

SYMBO	mm		
	MIN	NOM	MAX
A	4.37	4.57	4.70
A1	1.25	1.30	1.40
A2	2.20	2.40	2.60
b	0.70	0.80	0.95
b2	1.70	1.27	1.47
c	0.45	0.50	0.60
D	15.10	15.60	16.10
D1	8.80	9.10	9.40
D2	5.50	-	-
E	9.70	10.00	10.30
E3	7.00	-	-
e	2.54BSC		
e1	5.08BSC		
H1	6.25	6.50	6.85
L	12.75	13.50	13.80
L1	-	3.10	3.40
øP	3.40	3.60	3.80
Q	2.60	2.80	3.00